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N-Channel 200 V (D-S) Power MOSFET

PRODUCT SUMMARY V_{DS} (V) $R_{DS(on)}$ (m Ω) (Typ.) I_D (A)^a Q_g (Typ.) 200 12 at $V_{GS} = 10 \text{ V}$ 130 72 nC

FEATURES

- DT-Trench Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized
- 100 % R_g and UIS Tested

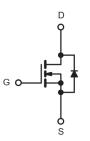


APPLICATIONS

· Primary Side Switch







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	LIMIT	UNIT				
Drain-Source Voltage		V _{DS}	200	V			
Gate-Source Voltage		V _{GS}	± 20				
Continuous Drain Current (T _J = 175 °C)	T _C = 25 °C		130	A			
	T _C = 100 °C	─ I _D	97				
Pulsed Drain Current		I _{DM}	390				
Single Avalanche Energy	E _{AS}	155	mJ				
Maximum Pawar Dissination	T _C = 25 °C	В	380 ^a	W			
Maximum Power Dissipation	T _C = 100 °C	$ P_{D}$	152ª] "			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	°C			

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	LIMIT	UNIT			
Junction-to-Ambient (PCB Mount) b,c	t ≤ 10 s	R _{thJA}	40	°C/W		
Junction-to-Case (Drain)	Steady State	R _{thJC}	0.4	- C/W		

a. Based on T_C = 25 °C. b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

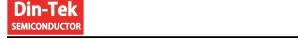


PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		-	-	V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2	-	4	V
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current		V _{DS} = 200 V, V _{GS} = 0 V	-	-	1	μА
	I _{DSS}	V _{DS} = 160 V, V _{GS} = 0 V, T _J = 125 °C	-	-	100	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	130	-	-	Α
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 30 A	-	12	16	mΩ
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 30 A	-	80	-	S
Dynamic ^b				1		
Input Capacitance	C _{iss}		-	5170	-	pF
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz	-	390	-	
Reverse Transfer Capacitance	C _{rss}		-	15	-	
Total Gate Charge ^c	Qg		-	72	-	nC
Gate-Source Charge ^c	Q _{gs}	V _{DS} = 100 V, V _{GS} = 10 V, I _D = 30 A	-	23	-	
Gate-Drain Charge ^c	Q _{gd}		-	13	-	
Gate Resistance	R _g	f = 1 MHz	-	6	-	Ω
Turn-On Delay Time ^c	t _{d(on)}		-	13	-	
Rise Time ^c	t _r	$V_{DD} = 100 \text{ V}, I_D = 30 \text{ A}, R_g = 2.5 \Omega$	-	48	-	ns
Turn-Off Delay Time ^c	t _{d(off)}	V _{GS} = 10 V	-	27	-	
Fall Time ^c	t _f		-	58	-	
Drain-Source Body Diode Ratings and	Characterist	tics ^b (T _C = 25 °C)				
Continuous Source-Drain Diode Current	Is	T _C = 25 °C	-	-	130	Α
Pulsed Current (t = 100 µs)	I _{SM}		-	-	390	Α
Forward Voltage ^a	V _{SD}	I _F = 30 A, V _{GS} = 0 V	-	-	1.2	V
Reverse Recovery Time	t _{rr}	1 20 A di/dt 100 A/:	-	185	-	ns
Reverse Recovery Charge	Q _{rr}	I _F = 30 A, di/dt = 100 A/μs	-	120	-	nC

Notes

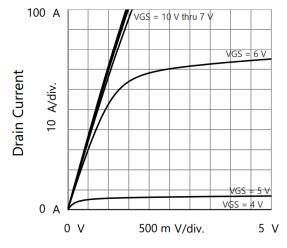
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

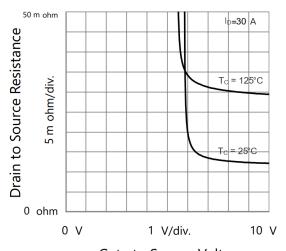


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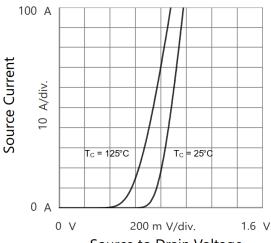
TYPICAL CHARACTERISTICS (25 C, unless otherwise noted)



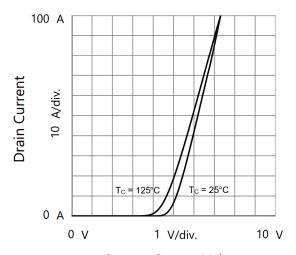
Drain to Source Voltage Output Characteristics



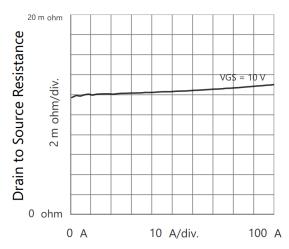
Gate to Source Voltage
Drain to Source Resistance vs. Gate to Source Voltage



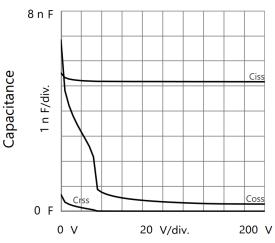
Source to Drain Voltage Body Diode Forward Characteristics



Gate to Source Voltage Transfer Characteristics



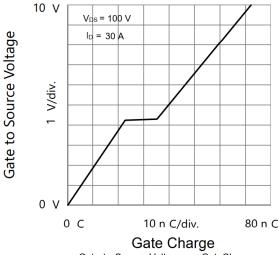
Drain Current
Drain to Source Resistance vs. Drain Current



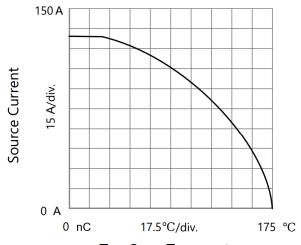
Drain to Source Voltage Capacitances



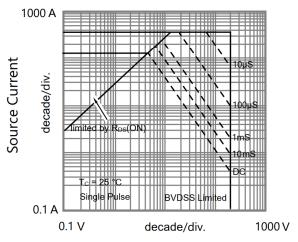
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



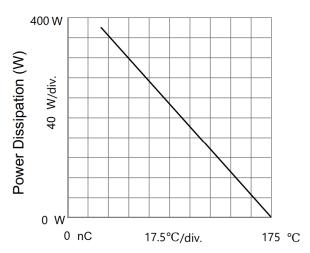
Gate to Source Voltage vs. GateCharge



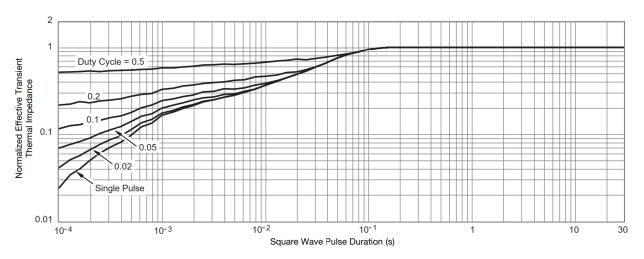
T_C - Case Temperature



Source to Drain Voltage Safe Operating Area, Junction-to-Ambient



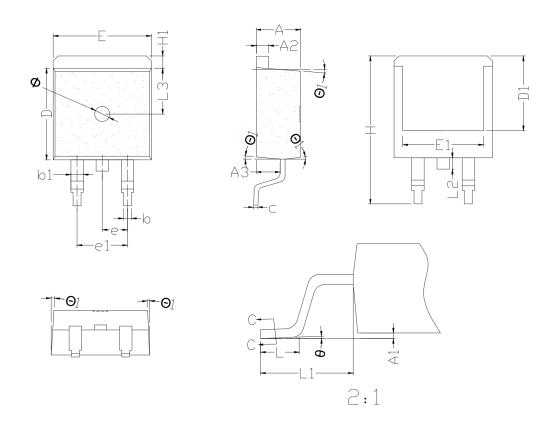
T_C - Case Temperature



Normalized Thermal Transient Impedance, Junction-to-Case



TO-263 PACKAGE OUTLINE



COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX	SYMBOL	MIN	TYP	MAX
Α	4.10	4.50	4.80	е	2.35	2.54	2.75
A1	0.00	0.10	0.30	e1	5.08REF		
A2	1.10	1.30	1.50	Н	14.50	15.15	16.00
A3	2.15	2.50	3.10	H1	1.00	1.28	1.75
b	0.60	0.80	1.05	L	1.80	2.23	2.90
b1	1.05	1.33	1.50	L1	4.30	4.75	5.50
С	0.33	0.50	0.66	L2	1.00	1.30	1.85
D	8.40	9.20	9.60	L3	0.90	4.65	9.00
D1		7.50REF		ф	0°	2°	5°
Е	9.60	10.02	10.80	φ1	2°	-	7°
E1	7.60	9.88	10.30	Φ	1.5BSC		





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